

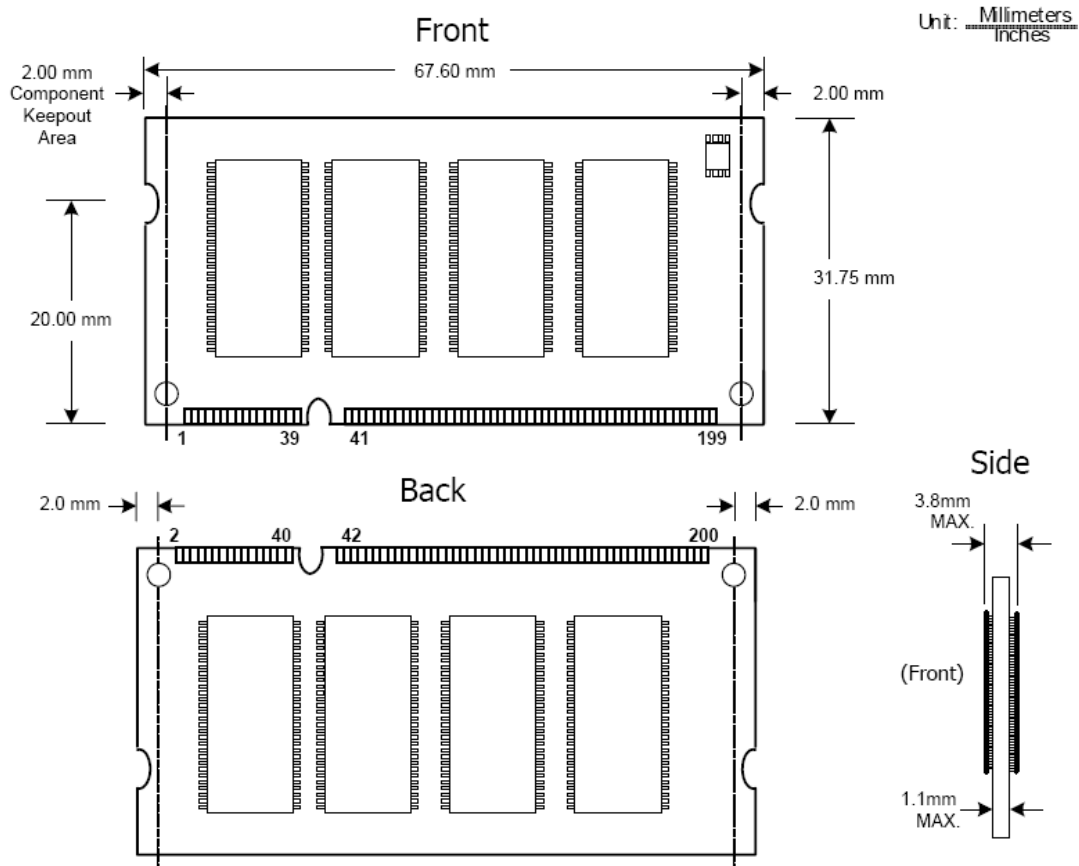
## Memory Module Data Sheet L6464S35

### 512MB 64M x 64-bit DDR266 (PC2100) SoDIMM

#### SPECIFICATIONS;

- 512MB (64M x 64-bit) Unbuffered DDR266 SoDIMM
- TSOP II 32M x 16 (8M x 16 bit x 4 Bank/200Mhz) x Eight DRAM
- 200-pin Small Outline Dual Inline memory module with Gold Plated Contacts
- Dimm Dimensions 67.6 x 31.75 x 3.8 (mm)
- Programmable CAS Latency Supported - CL 2.5
- Row Cycle Time (tRC) - 60ns
- Auto Refresh Cycle Time (tRFC)- 72ns (min.)
- Row Active Time (tRAS) - 42ns
- Clock Cycle Time (tCK) - 6ns
- Power Supply Voltage - 2.5V (+/- .01V)
- Operating Temperature (TA) - 0~70 Celsius

#### PACKAGE DIMENSIONS



**NOTE:** The module described in this data sheet is one of several configurations available under this part number. All configurations are compatible but the DRAM combination and the module height may vary from what is described.